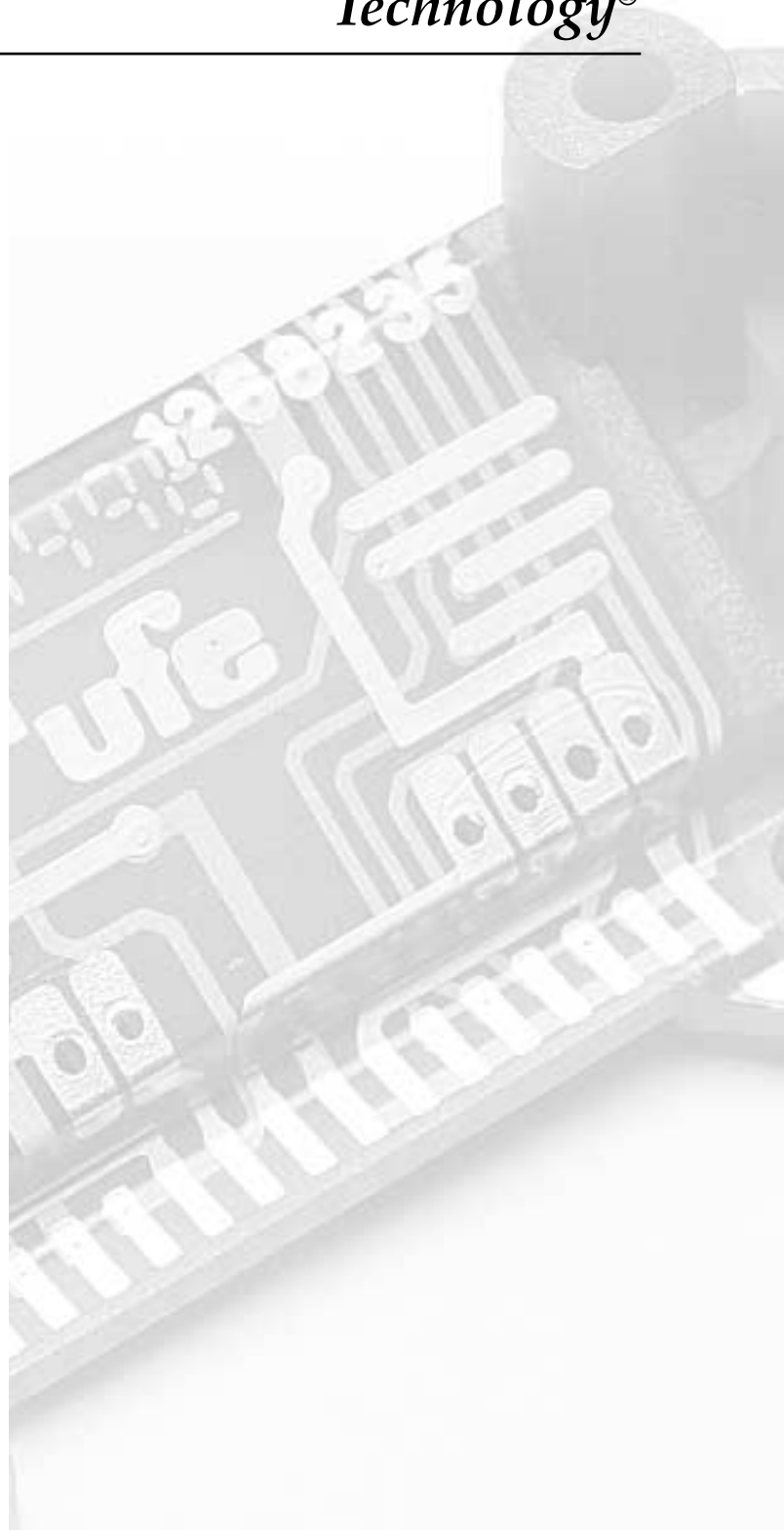




UFE Molded Circuit Technology[®]

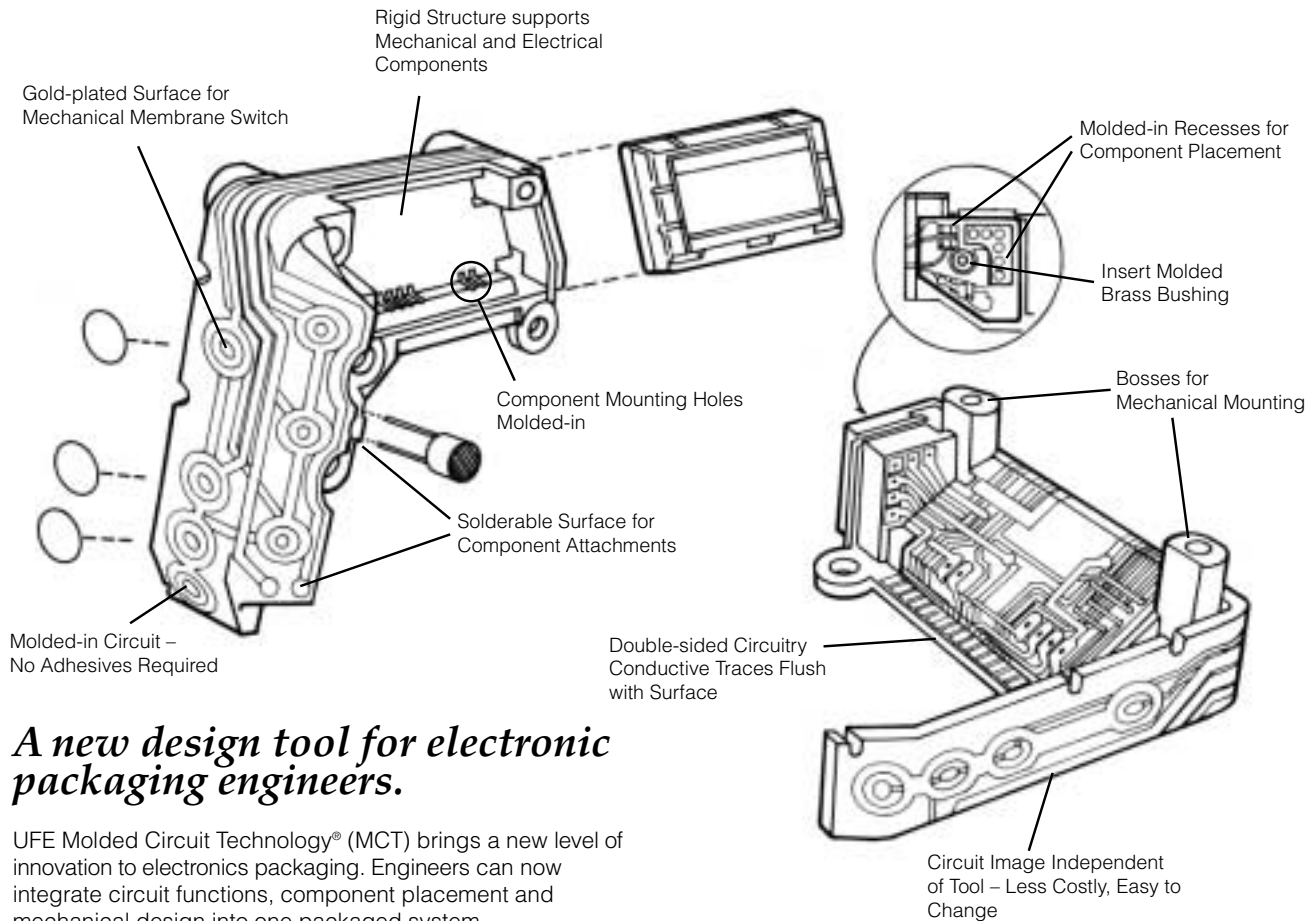
*A Systems Packaging
Solution for Advanced
Electronics*

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UFE Molded Circuit Technology®

Integrate electronic, mechanical and circuit functions in one assembly



A new design tool for electronic packaging engineers.

UFE Molded Circuit Technology® (MCT) brings a new level of innovation to electronics packaging. Engineers can now integrate circuit functions, component placement and mechanical design into one packaged system.

The MCT process combines today's flexible circuit and injection molding technology. Either single or double-sided flexible circuits can be formed into 2D, 2-1/2D, or 3D shapes. They are then insert molded in a plastic injection molding press. Upon molding, the circuit is no longer flexible, but an integral part of its own supporting structure.

For design assistance, request our UFE Molded Circuit Technology® *Design Guide*.

Applications for UFE MCT include:

- Telecommunications
 - Antennas
 - Hand-held
- Automotive
 - Sensors
 - 3D Antennas
- Industrial Electronics
 - Harsh Environments
- Industrial Instrumentation
 - Sensor/Electronics Integration
- Medical Device and Instrumentation
- Consumer Electronics



This handheld device uses MCT to replace 15 parts and features double-sided 3D flex circuitry with gold overplating for corrosion and solderability. Military and outdoor applications.

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